

Tantalum-Clad Copper Foil

Catlog Number: BMBCC-0064

• Description

Composite foil featuring a tantalum surface for acid resistance and a copper core for maximum electronic conductivity.

• Basic Information

Substrate Material: Ta-Cu-Ta

Purity (%): Ta: 5 μ m (each)

Thickness (μ m): 20 (Total)

Width (mm): 100

Areal Density (g/m²): 190 - 210

Tensile Strength (MPa): \geq 320

Elongation (%): \geq 5.0

Surface Finish: Roll Clad

Surface Roughness (Ra, μ m): \leq 0.30

Electrical Resistivity (Ω ·m): 1.9×10^{-8}

Thermal Conductivity (W/m·K): 350

Melting Point ($^{\circ}$ C): 1083 (Cu)

Oxidation Resistance (Temp/Time): 400 $^{\circ}$ C / 30min

Coating Type: Tantalum Cladding

Coating Thickness (μ m): 5

Core ID (mm): 76

Standard Length (m): 2

Operating Voltage Range (V): 0.0 - 6.0

Application Compatibility: Extreme Acid Cells

Storage Requirements: Dry / Sealed

Form Factor: Roll

Hydrophilic Properties: Ultra-Inert

Compliance / Grade: Industrial Grade

 For Research or Industrial Raw Materials, Not For Personal Medical Use!